1. Record Nr. UNISA996391006103316

Autore	Becon Thomas <1512-1567.>
Titolo	A newe pathway vnto praier [[electronic resource]] : ful of much godly frute and christe[n] knowledge, lately made by Theodore Basille
Pubbl/distr/stampa	[Imprynted at London, : In Botulphe lane at the sygne of the whyte Beare, by me Iohn Mayler for Iohn Gough, Anno D[omi]ni. 1542]
Descrizione fisica	[296] p
Soggetti	Prayer
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Theodore Basille = Thomas Becon. Imprint from colophon. Signatures: A-S Tâ´. Reproduction of the original in Cambridge University Library.
Sommario/riassunto	eebo-0021

2. Record Nr. UNINA9910346840003321

Autore	Verd Jaume
Titolo	Development of CMOS-MEMS/NEMS Devices / Jaume Verd, Jaume Segura
Pubbl/distr/stampa	MDPI - Multidisciplinary Digital Publishing Institute, 2019 Basel, Switzerland : , : MDPI, , 2019
ISBN	9783039210695 3039210696
Descrizione fisica	1 electronic resource (165 p.)
Soggetti	History of engineering and technology
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Formato	Materiale a stampa
Livello bibliografico	Monografia
Sommario/riassunto	Micro and nano-electro-mechanical system (M/NEMS) devices constitute key technological building blocks to enable increased additional functionalities within Integrated Circuits (ICs) in the More-Than-Moore era, as described in the International Technology Roadmap for Semiconductors. The CMOS ICs and M/NEMS dies can be combined in the same package (SiP), or integrated within a single chip (SoC). In the SoC approach the M/NEMS devices are monolithically integrated together with CMOS circuitry allowing the development of compact and low-cost CMOS-M/NEMS devices for multiple applications (physical sensors, chemical sensors, biosensors, actuators, energy actuators, filters, mechanical relays, and others). On-chip CMOS electronics integration can overcome limitations related to the extremely low-level signals in sub-micrometer and nanometer scale electromechanical transducers enabling novel breakthrough applications. This Special Issue aims to gather high quality research contributions dealing with MEMS and NEMS devices monolithically integrated with CMOS, independently of the final application and fabrication approach adopted (MEMS-first, interleaved MEMS, MEMS-last or others).]